**Product data sheet** 

# 1. General description

Planar Schottky barrier rectifier encapsulated in a CFP2-HP (SOD323HP) power flat lead Surface-Mounted Device (SMD) plastic package.

### 2. Features and benefits

- Low forward voltage
- High power capability due to clip-bond package
- · Power flat lead plastic package with exposed heatsink for optimal thermal connection
- Qualified according to AEC-Q101 and recommended for use in automotive applications

# 3. Applications

- · Low voltage rectification
- · High efficiency DC-to-DC conversion
- Freewheeling
- · Reverse polarity protection
- OR-ing

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; f = 20 kHz; square wave; T <sub>sp</sub> $\leq$ 172 °C		-	-	1	A
$V_R$	reverse voltage	T <sub>j</sub> = 25 °C		-	-	30	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 1 A; pulsed; T <sub>j</sub> = 25 °C	[1]	-	430	500	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 30 V; pulsed; T <sub>j</sub> = 25 °C	[1]	-	10	60	μΑ
		$V_R = 30 \text{ V}$ ; pulsed; $T_j = 125 ^{\circ}\text{C}$	[1]	-	5	25	mA

<sup>[1]</sup> Very short pulse, in order to maintain a stable junction temperature.

# 5. Pinning information

**Table 2. Pinning information** 

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]		
2	A	anode	Transparent top view  CFP2-HP (SOD323HP)	K <b>-}</b> € - A sym001

[1] The marking bar indicates the cathode.



# 6. Ordering information

#### **Table 3. Ordering information**

Type number	Package	kage				
	Name	Description	Version			
PMEG3010EXD-Q	CFP2-HP	SOD323HP: plastic surface-mounted package with solderable lead ends; 2.2 mm x 1.3 mm x 0.68 mm body	SOD323HP			

## 7. Marking

#### Table 4. Marking codes

Type number	Marking code
PMEG3010EXD-Q	8L

# 8. Limiting values

### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	T <sub>j</sub> = 25 °C		-	30	V
I <sub>F</sub>	forward current	δ = 1; T <sub>sp</sub> ≤ 171 °C		-	1.4	Α
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; f = 20 kHz; square wave; T <sub>sp</sub> ≤ 172 °C		-	1	А
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p = 8.3 \text{ ms}$ ; half sine wave; $T_{j(init)} = 25 \text{ °C}$		-	25	А
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	-	0.65	W
			[2]	-	1.2	W
Tj	junction temperature			-	175	°C
T <sub>amb</sub>	ambient temperature			-55	175	°C
T <sub>stg</sub>	storage temperature			-65	175	°C

<sup>[1]</sup> Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

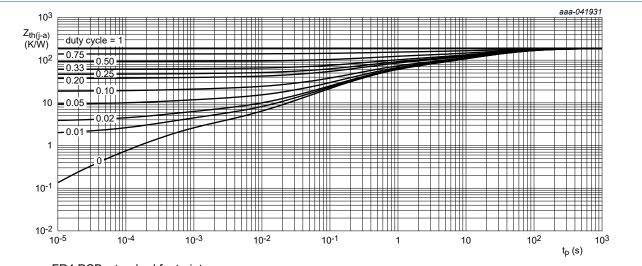
<sup>[2]</sup> Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

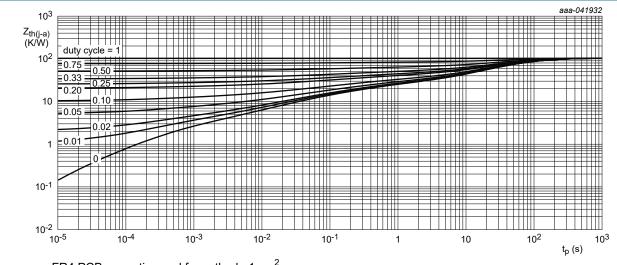
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from	in free air	[1] [2]	-	-	230	K/W
junction to ambient	junction to ambient		[1] [3]	-	-	125	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	6	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Soldering point of cathode tab.



FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

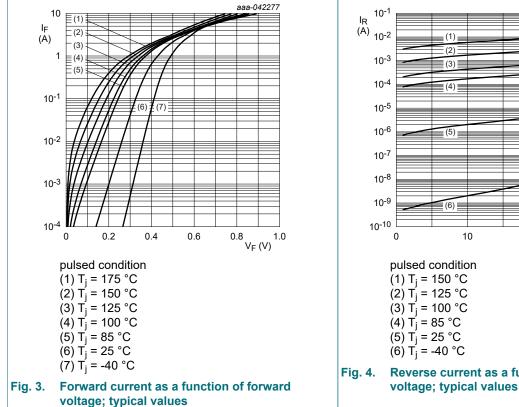
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

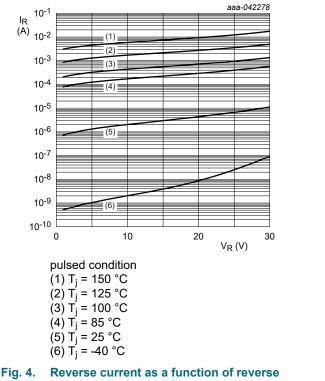
### 10. Characteristics

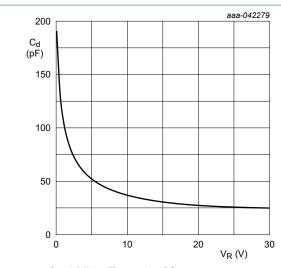
Table 7 Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 3$ mA; pulsed; $T_j = 25$ °C	[1]	30	-	-	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.5 A; pulsed; T <sub>j</sub> = 25 °C	[1]	-	390	450	mV
		I <sub>F</sub> = 1 A; pulsed; T <sub>j</sub> = 25 °C	[1]	-	430	500	mV
		I <sub>F</sub> = 1 A; pulsed; T <sub>j</sub> = -40 °C	[1]	-	490	560	mV
		I <sub>F</sub> = 1 A; pulsed; T <sub>j</sub> = 125 °C	[1]	-	330	395	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 30 V; pulsed; T <sub>j</sub> = 25 °C	[1]	-	10	60	μΑ
		V <sub>R</sub> = 30 V; pulsed; T <sub>j</sub> = 125 °C	[1]	-	5	25	mA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C		-	105	-	pF
		V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C		-	37	-	pF
t <sub>rr</sub>	reverse recovery time step recovery	$I_F = 0.5 \text{ A}; I_R = 1 \text{ A}; I_{R(meas)} = 0.25 \text{ A};$ $T_j = 25 \text{ °C}$		-	3.1	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 100 \text{ A/}\mu\text{s}; I_F = 1 \text{ A}; V_R = 30 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$		-	6.3	-	ns
I <sub>RM</sub>	peak reverse recovery current			-	0.26	-	Α
Q <sub>rr</sub>	reverse recovery charge			-	1	-	nC
$V_{FRM}$	peak forward recovery voltage	$I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		-	390	-	mV

[1] Very short pulse, in order to maintain a stable junction temperature.

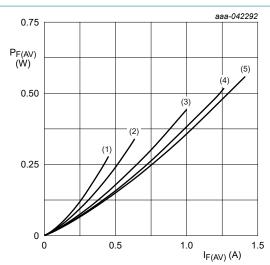






 $f = 1 MHz; T_{amb} = 25 °C$ 

Fig. 5. Diode capacitance as a function of reverse voltage; typical values



T<sub>i</sub> = 100 °C

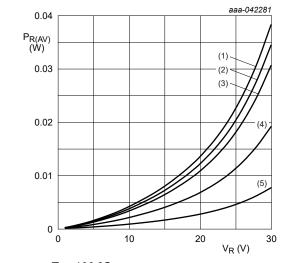
 $(1) \delta = 0.1$ 

 $(2) \delta = 0.2$ 

 $(3) \delta = 0.5$ 

 $(4) \delta = 0.8$ (5)  $\delta = 1$  (DC)

Fig. 6. Average forward power dissipation as a function of average forward current; typical values

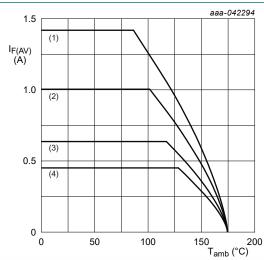


 $T_j = 100 \,^{\circ}\text{C}$ (1)  $\delta = 1$ (2)  $\delta = 0.9$ 

 $(3) \delta = 0.8$  $(4) \delta = 0.5$ 

 $(5) \delta = 0.2$ 

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

 $T_j = 175 \,{}^{\circ}\text{C}$ 

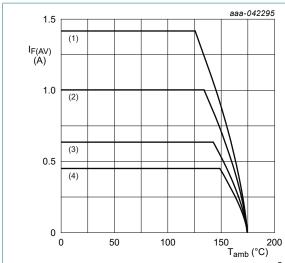
 $(1) \delta = 1 (DC)$ 

(2)  $\delta$  = 0.5; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

 $(4) \delta = 0.1$ ; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

T<sub>i</sub> = 175 °C

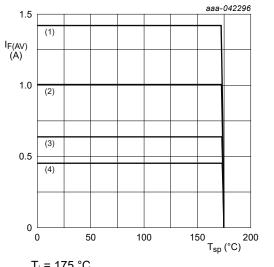
 $(1) \delta = 1 (DC)$ 

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

 $(4) \delta = 0.1$ ; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



 $T_j = 175$  °C (1)  $\delta = 1$  (DC) (2)  $\delta = 0.5$ ; f = 20 kHz (3)  $\delta = 0.2$ ; f = 20 kHz (4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

# 11. Test information

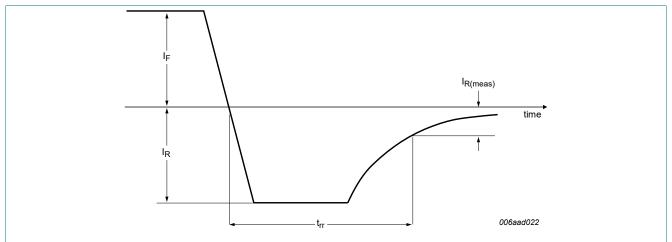


Fig. 11. Reverse recovery definition; step recovery

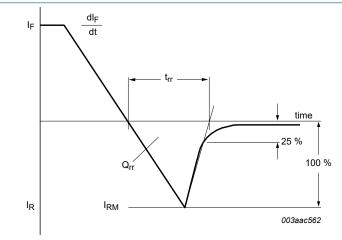


Fig. 12. Reverse recovery definition; ramp recovery

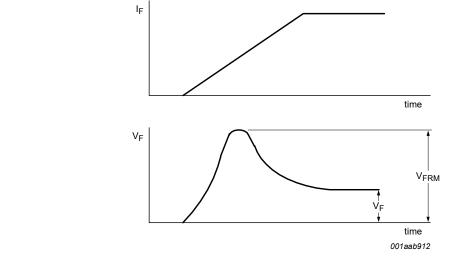
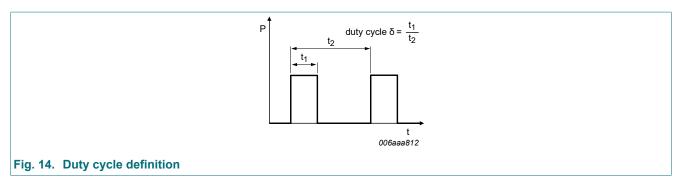


Fig. 13. Forward recovery definition

**Product data sheet** 

7 / 13



The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current

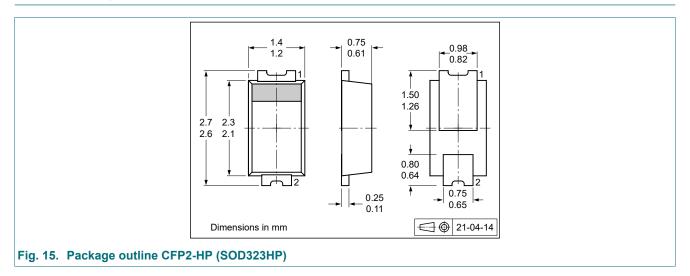
 $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_{M} \times \sqrt{\delta}$ 

with  $I_{\text{RMS}}$  defined as RMS current.

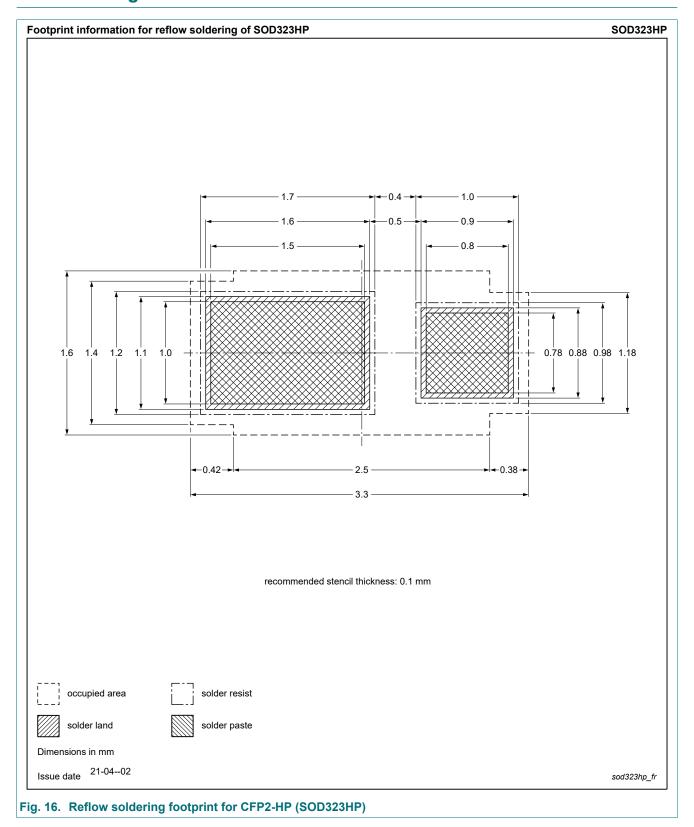
### **Quality information**

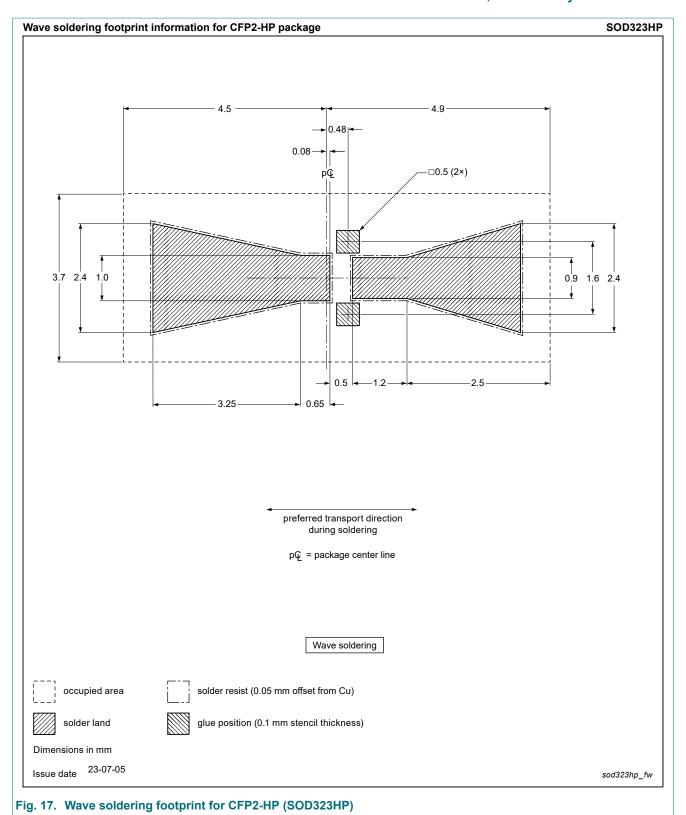
This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

# 12. Package outline



# 13. Soldering





PMEG3010EXD-Q

# 14. Revision history

#### Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG3010EXD-Q v.1	20250123	Product data sheet	-	-

### 15. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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12 / 13

## **Contents**

1.	General description	1
2.	Features and benefits	1
3.	Applications	. 1
4.	Quick reference data	1
5.	Pinning information	1
6.	Ordering information	2
7.	Marking	2
8.	Limiting values	. 2
9.	Thermal characteristics	. 3
10.	Characteristics	4
11.	Test information	7
12.	Package outline	8
13.	Soldering	9
14.	Revision history	11
	Legal information	

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13 / 13

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